

**pcim**  
ASIA



**28 – 30 August 2024**

Shenzhen World Exhibition &  
Convention Center, China

International Exhibition and Conference for  
Power Electronics, Intelligent Motion, Renewable  
Energy and Energy Management

**Call for Papers**

[www.pcimasia-expo.com](http://www.pcimasia-expo.com)

Proceedings Publisher



# PCIM Asia Conference 2024 Advisory Board

## General Conference Director



» Being able to identify the industry's development trends, this makes the PCIM Asia Conference platform even more important for industry players to focus on developing the right products and technologies to meet the demands of the future. «

Leo Lorenz, ECPE, DE

## Board of Directors



Enrique J. Dede,  
Smart Induction  
Converter Technologies,  
ES



Naoto Fujishima,  
Fuji Electric, JP



Yongdong Li,  
Tsinghua University,  
CN



Jinjun Liu,  
Xi'an Jiaotong  
University, CN



Gourab Majumdar,  
Mitsubishi Electric  
Corporation, JP



Abhijit D. Pathak,  
ADP-Power LLC,  
USA



Norbert Pluschke,  
Semikron Danfoss,  
HKSAR, CN



Xinbo Ruan,  
Nanjing University  
of Aeronautics and  
Astronautics, CN



Tianhao Tang,  
Shanghai Maritime  
University, CN



Dehong Xu,  
Zhejiang University,  
CN



Dianguo Xu,  
Harbin Institute  
of Technology, CN



Jianping Ying,  
Delta Electronics,  
CN



Dapeng Zheng,  
Shenzhen Hopewind  
Electric, CN

# Technical Committee



**Jean-Paul Beaudet,**  
Schneider Electric,  
FR



**Yijen Chan,**  
Cyntec Co., Ltd,  
TW, CN



**Min Chen,**  
Zhejiang University,  
CN



**Youngchul Choi,**  
Panjit International,  
USA



**Ziyang Chen,**  
Infineon Technologies,  
CN



**Jinsong Kang,**  
Tongji University,  
CN



**Yong Kang,**  
Huazhong University of  
Science and Technology,  
CN



**Teng Liu,**  
China Southern Power  
Grid Electric Power  
Research Institute, CN



**Haihui Luo,**  
Zhuzhou CRRC Times  
Semiconductor, CN



**Yu-Kang Lo,**  
LITE-ON Technology,  
TW, CN



**Meiqin Mao,**  
Hefei University of  
Technology, CN



**Gaosheng Song,**  
Great China Mitsubishi  
Electric Semiconductor, CN



**Yi Tang,**  
Starpower Semiconductor,  
CN



**Shunli Wang,**  
Southwest University of  
Science and Technology,  
CN



**Xuhui Wen,**  
Institute of Electrical  
Engineering, Chinese  
Academy of Sciences, CN



**James Yin-Chin Wu,**  
Hosonic Electronic  
Corporation Group,  
TW, CN



**Lie Xu,**  
Tsinghua University,  
CN



**Gang Yao,**  
Shanghai Maritime  
University, CN



**Xing Zhang,**  
Hefei University of  
Technology, CN



**Guoqiang Zhang,**  
Harbin Institute of  
Technology, CN



**Miao Zhu,**  
Shanghai Jiao Tong  
University, CN

# Become a Speaker

You are forward-thinking expert in the field of power electronics and would like to inspire an audience of around 500 conference attendees with your latest developments and research findings?

**Join us at PCIM Asia Conference and inspire others with your ideas!**

## Why be a speaker?

→ All the selected papers will be published in PCIM Asia Conference proceeding, and will have the opportunity to archive in reputable databases: Ei Compendex, IEEE Xplore, IET Inspec-Direct and Scopus.



→ Exchange experiences with power electronics experts and expand your knowledge on current and upcoming industry trends.

→ Establish new contacts and take advantage of networking opportunities with global leading industry brands.



## Dates to remember

- Submission of abstracts before **4 March 2024**
- Notification of acceptance on **May 2024**
- Submission of full paper before **20 June 2024**
- ★ The presentation language is ENGLISH



## Chance to win the awards

The awards will be selected by the Advisory Board from the accepted papers, and will be granted at PCIM Asia Conference 2024.



**pcim Asia**  
Best Paper Award

1 winner  
Prize with RMB 8,000/each



**pcim Asia**  
Young Engineer Award

1 winner  
Prize with RMB 8,000/each



**pcim Asia**  
University Scientist Award

5 winner  
Prize with RMB 2,000/each

All details at  
[www.pcimasia-expo.com](http://www.pcimasia-expo.com)

# Topics of Interest

## 1. Advanced Power Semiconductors

- 1.1 High Power Semiconductors
- 1.2 MOSFETs, IGBTs, FREDs & Schottkys
- 1.3 Power Modules and Power Hybrids
- 1.4 SiC Devices
- 1.5 GaN Devices
- 1.6 Other Wide Bandgap Devices
- 1.7 Power Supply Control IC and Power Management ICs
- 1.8 Gate Driver and Device Protection
- 1.9 IPM and Power Electronic Building Blocks

## 2. Packaging and Reliability

- 2.1 Packaging and Interface Technologies
- 2.2 Advanced Cooling Systems
- 2.3 Thermal Management and Simulations
- 2.4 Power Electronic Components Reliability and Life Time Prediction
- 2.5 Power Embedding
- 2.6 High Power Density Designs
- 2.7 Design Automation and Methodology

## 3. Passive Components and Integration

- 3.1 Higher Frequency and Low Loss Materials & Techniques for Inductors and Capacitors
- 3.2 Planar Inductors and Transformers and Thin Film Magnetic Component
- 3.3 Filters and Passive Integration

## 4. AC/DC Converter

- 4.1 High Efficiency/High Density Power Converters/Inverters
- 4.2 Resonant and Quasi Resonant Topologies for Power Supplies
- 4.3 Stand-alone Power Supplies (Adapters) and on Board Supplies
- 4.4 New Topologies (Single Switch, Phase Shift, ZVS, ZCS, ZVZCS)

## 5. DC/DC Converter

- 5.1 DC/DC Converter Topologies for Enhanced Efficiency and Control
- 5.2 Synchronous Rectification
- 5.3 Smart Battery Management Concepts
- 5.4 Point of Load Converters
- 5.5 New Topologies for Distributed Power Supply Systems (Single or Multi- Stage Architecture, ZVS, ZCS, ZVZCS)

## 6. Digital Power Conversion

- 6.1 PMBus and other Digital Power Control Protocols
- 6.2 Digital Control for Power Converters
- 6.3 Advantages of Digital Power Conversion and Associated Challenges
- 6.4 System on a Chip (SOC)
- 6.5 Energy Harvesting

## 7. Motor Drive & Motion Control

- 7.1 Home Appliances
- 7.2 Small Power Motor "General Purpose Drive" with Highly Sophisticated Control Strategies and Low Cost Solutions
- 7.3 New Converter/Inverter Types for Single- and Three Phase Systems
- 7.4 Advanced Motor Concepts for Industrial Application and Traction Drives
- 7.5 New Control Architectures DSP, Microcontroller or FPGA
- 7.6 Advanced Sensor Concepts for Motor Drives
- 7.7 Intelligent Motion Control and Architecture

## **8. High Frequency Power Electronic Converters and Inverters**

- 8.1 Thermal Design, Packaging and EMI Issues
- 8.2 Sensors Specific to Power Electronics  
(e.g. Voltage, Current, Power, Frequency, Phase, Temperature)
- 8.3 Techniques to Reduce Switching Losses to Improve Efficiency and Reduce Size and Weight
- 8.4 Wireless Power Transfer

## **9. Automotive Power Electronics and Electrified Transportation**

- 9.1 Hybrid / Electric Vehicle
- 9.2 MOSFET, IGBT and SiC Modules in Motor Traction and Propulsion Applications
- 9.3 DC/DC Conversion in Transportation Systems
- 9.4 Bidirectional DC/DC Converters
- 9.5 Electronics for Powertrain and Power Management
- 9.6 Energy Storage and Management, including Battery Types, Super Capacitors and Fly Wheels
- 9.7 DC Circuit Breaker
- 9.8 Charging Station Technology

## **10. System Reliability**

- 10.1 Reliability and Health Management of Power Electronic Components and Systems
- 10.2 Fail-safe and Fault-tolerant Applications
- 10.3 Redundancy Concepts in Power Electronics
- 10.4 Life Cycle Design and Cost Analysis

## **11. Power Quality Solutions**

- 11.1 UPS Systems and Inverters
- 11.2 Active Power Filter (APF), DVR, SVG
- 11.3 Energy Storage System  
(Battery Technologies, Flywheel, Super (ultra) Capacitors)
- 11.4 Harmonics and Power Factor Correction
- 11.5 Electromagnetic Compatibility and Immunity

## **12. Smart Grid Power Electronics**

- 12.1 Grid Inverter Control
- 12.2 Battery Charging and V2G
- 12.3 Energy Storage System and Control
- 12.4 Micro-Grid
- 12.5 Solid State Transformers
- 12.6 Medium Voltage Multilevel Converters
- 12.7 Modular Multilevel Converters
- 12.8 Novel Converter Topologies
- 12.9 Wind Energy Systems
- 12.10 Solar and Photovoltaic Energy Systems
- 12.11 Communication, Cyber Security and Artificial Intelligence

## **13. Power Electronics in Transmission Systems**

- 13.1 FACTS
- 13.2 Converters for Offshore/Onshore HVDC Links
- 13.3 Power Generation, Transmission and Distribution
- 13.4 DC Grids
- 13.5 HVDC Systems
- 13.6 Digital Twin for Transmission Equipment

# PCIM Asia Conference 2023 Speakers



\* No specific order

## Your Contact

PCIM Asia Conference

Tel: +86 20 3825 1558 Ext 246

Email: [pcim-con@china.messefrankfurt.com](mailto:pcim-con@china.messefrankfurt.com)

Web: [www.pcimasia-expo.com](http://www.pcimasia-expo.com)

## Organizer



Guangzhou Guangya Messe Frankfurt Co Ltd.  
UnitB 3107, Center Plaza, No.161 Linhe Road West,  
Tianhe District, Guangzhou  
Phone: +86 20 38251558  
Fax: +86 20 38251400  
[pcim-con@china.messefrankfurt.com](mailto:pcim-con@china.messefrankfurt.com)

## Partner



Messe Frankfurt Group

Mesago Messe Frankfurt GmbH  
Rotebuehlstr. 83-85  
70178 Stuttgart  
Phone: +49 711 61946-0  
Fax: +49 711 61946-90  
[pcim@mesago.com](mailto:pcim@mesago.com)  
[pcim-europe.com](http://pcim-europe.com)



WeChat